2SD1450

Silicon NPN epitaxial planar type

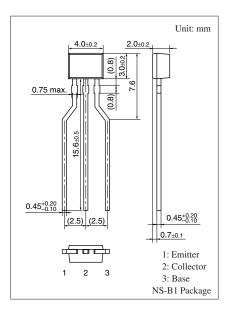
For low-frequency amplification

Features

- Optimum for high-density mounting
- Allowing supply with the radial taping
- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$

Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|------------------|-------------|------|
| Collector-base voltage (Emitter open) | V _{CBO} | 25 | V |
| Collector-emitter voltage (Base open) | V _{CEO} | 20 | V |
| Emitter-base voltage (Collector open) | V _{EBO} | 12 | V |
| Collector current | I _C | 0.5 | А |
| Peak collector current | I _{CP} | 1 | А |
| Collector power dissipation | P _C | 300 | mW |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | T _{stg} | -55 to +150 | °C |



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

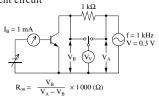
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--|----------------------|--|-----|------|------|------|
| Collector-base voltage (Emitter open) | V _{CBO} | $I_{\rm C} = 10 \ \mu A, \ I_{\rm E} = 0$ | 25 | | | V |
| Collector-emitter voltage (Base open) | V _{CEO} | $I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$ | 20 | | | V |
| Emitter-base voltage (Collector open) | V _{EBO} | $I_E = 10 \ \mu A, I_C = 0$ | 12 | | | V |
| Collector-base cutoff current (Emitter open) | I _{CBO} | $V_{CB} = 25 \text{ V}, I_E = 0$ | | | 100 | nA |
| Forward current transfer ratio *1 | h _{FE1} *2 | $V_{CE} = 2 V, I_C = 0.5 A$ | 200 | | 800 | |
| | h _{FE2} | $V_{CE} = 2 V, I_C = 1 A$ | 60 | | | |
| Collector-emitter saturation voltage *1 | V _{CE(sat)} | $I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 20 \text{ mA}$ | | 0.13 | 0.40 | V |
| Base-emitter saturation voltage *1 | V _{BE(sat)} | $I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 20 \text{ mA}$ | | | 1.2 | V |
| Transition frequency | f _T | $V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$ | | 200 | | MHz |
| Collector output capacitance | C _{ob} | $V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 10 | | pF |
| (Common base, input open circuited) | | | | | | |
| ON resistance *3 | R _{on} | | | 0.6 | | Ω |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

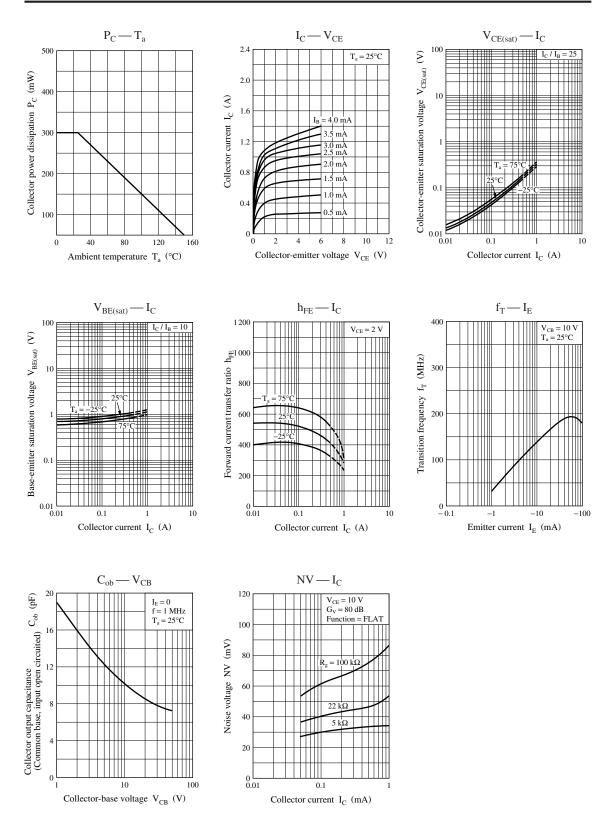
2. *1: Pulse measurement

| Rank | R | S | Т | No rank |
|------------------|------------|------------|------------|------------|
| h _{FE1} | 200 to 350 | 300 to 500 | 400 to 800 | 200 to 800 |

*3: R_{on} Measurement circuit



Panasonic



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